

TECHNICAL DATA SHEET THERMOTOP AL

DESCRIPTION

THERMOTOP AL is a PIR (polyisocyanurate) thermal insulation board, faced on both sides with aluminium foil.

MAIN APPLICATIONS

- ✓ Thermal insulation of single-layer and multi-layer pitched roofs;
- ✓ Thermal insulation of walkable, non-walkable, and green flat roofs;
- ✓ Thermal insulation of cold and heated floors;
- ✓ Thermal insulation for foundations, slabs, and parapets;
- ✓ Thermal insulation of industrial roofs with a slope of up to 7%.

TECHNICAL CHARACTERISTICS:

Characteristics (standard)	Description	Symbol (UM)	Values (some characteristics depend on the thickness)															
			20	30	40	50	60	70	80	90	100	120	140	150	160	170	180	200
Medium thermal conductivity [EN 12667]	Value determined at 10°C	$\lambda_{90/90,1}$ [W/mK]	0.021															
Declared heat transfer	$U_D = \lambda_D / d$	U_D [W/m ² K]	1,05	0,70	0,53	0,42	0,35	0,30	0,26	0,23	0,21	0,18	0,15	0,14	0,13	0,12	0,12	0,11
Declared thermal resistance [EN 12667]	$RD = d / \lambda_D$	R_D [m ² K/W]	0,95	1,43	1,90	2,38	2,86	3,33	3,81	4,28	4,76	5,71	6,67	7,14	7,62	8,10	8,57	9,52
Tensile strength across the faces [EN 1607]	TR 100	[kPa]	≥100															
Compression strength SR EN ISO 29469	Value determined at 10% deformation CS(10\Y)150	[kPa]	≥150															
Dimensional stability at a certain temperature and humidity [EN 1609]	48h at 70°C DS(TH) – level 3 Value determined at 10°C	[% length and width]	≤2															
		$\lambda_{90/90,1}$ [W/mK]	≤6															
Classification of reaction to fire [EN 13501-1] [EN 11925-2]		Euroclass	E															

Water Absorption [EN 1609]	Partial immersion	W_{sp} [kg/m ²]	Less than 0.1
Water vapour diffusion resistance factor [EN 12086]		μ	37,52
Flatness deviation [EN 825]	Value	W_b [kg/m ²]	≤5 for surfaces ≤ 0.75 m² ≤10 for surfaces > 0.75 m²

Tolerances and Notes

Tolerances (EN 13165)	Thickness	T2 [mm]	<50 ±2 mm	From 50 to 75 ±3 mm	>75 ±5 mm, -3 mm
	Dimensions		<1000 ±5 mm	From 1000 to 2000 ±7,5 mm	From 2001 to 4000 ± 10 mm
Notes	Stability at temperature	THERMOTOP boards are used at temperatures between -40°C and +110°C. For short periods of time, they can resist up to 200 °C without problems. Long exposure to high temperatures can cause deformation of foam or faces without cause sublimation.			
	Aspect	On small portions, peeling between the faces and the foam can appear, as in some places there can be non-uniformities of the foam support resulting from the production process, without influencing in any way the physical-mechanical characteristics of the panels.			